UL Product iQ®

ZPMV2.E488074 - Wiring, Printed - Component

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E488074

Type	Cond Width Min mm	Cond Width Min Edge mm	Cond Thk mic	SS/ DS/ DSO	Max Area Diam mm	Report date After 2022-01-01	Surface Mount Technology	Assembly Solder Process Temp °C	Assembly Solder Process Cycles	Solder Limits °C	Solder Limits sec	Max Oper Temp °C	Flame Class	Meets UL796 DSR	CTI
Multilayer printed wiring boards															
JDB-M(ASP1)	0.075	0.1	12 Int:68	DS	50.8	No	-	260	2	288	10	130	V-0	All	*
JDB-M1(ASP1)	0.13	0.20	17 Int:68	DS	50.8	Yes	Yes	260	2	288	10	130	V-0	All	*
JDB-M2(ASP1)	0.16	0.18	17 Int:34	DS	50.8	Yes	Yes	260	2	288	10	130	V-0	All	*
Single layer Metal Base printed wiring boards															
JDB-A1(ASP1)	0.13	0.20	17	SS	50.8	Yes	Yes	260	1	288	10	90	V-0	All	0
JDB-A2(ASP1)	0.13	0.20	17	SS	50.8	Yes	Yes	260	1	288	10	130	V-0	All	0
Single layer Metal Base printed wiring boards, flammability only recognition															
JDB-A3(ASP1)	-	-	-	DS	-	Yes	Yes	260	2	288	10	-	V-0	-	-
Single layer printed wiring boards															
JDB-D(ASP1)	0.075	0.1	12	DS	50.8	Yes	Yes	260	2	288	10	130	V-0	All	*
JDB-H1(ASP1)	0.13	0.20	17	DS	50.8	Yes	Yes	260	2	288	10	130	V-0	All	*
Single Side Multilayer Metal Base printed wiring boards															
JDB-D1(ASP1)	0.12	0.15	17 Int:55	SS	50.8	Yes	Yes	260	2	288	10	90	V-0	▲	*

* - CTI marking is optional and may be marked on the printed wiring board.

ASP1 - Assembly Solder process evaluated to IPC-TM-650, 2.6.27 Thermal Stress Assembly Simulation.

Marking: Company nameor file number and type designation. May be followed by a suffix to denote factory identification or

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